

## Materials Declaration

|                  |          |
|------------------|----------|
| <b>Package</b>   | SOIC     |
| <b>Body Size</b> | 300 mils |
| <b>LeadCount</b> | 28       |
| <b>Option</b>    | Pb Free  |

### Molding Compound

| Item             | % of Compound | Weight (g) | PPM    |
|------------------|---------------|------------|--------|
| Epoxy resin      | 10            | 5.26 E-02  | 66907  |
| SiO2 Filler      | 85            | 4.47 E-01  | 568714 |
| Phenol Resin     | 3             | 1.58 E-02  | 20072  |
| Antimony_Sb2O3   | 1.5           | 7.89 E-03  | 10036  |
| Brominated Resin | 0.5           | 2.63 E-03  | 3345   |

### Leadframe

| Item | % of Leadframe | Weight (g) | PPM    |
|------|----------------|------------|--------|
| Cu   | 97.5           | 2.15 E-01  | 272841 |
| Fe   | 2.35           | 5.17 E-03  | 6576   |
| P    | 0.03           | 6.60 E-05  | 84     |
| Zn   | 0.12           | 2.64 E-04  | 336    |

### Internal Leadframe Plating

| Item | % of Plating | Weight (g) | PPM  |
|------|--------------|------------|------|
| Ag   | 100          | 1.92 E-03  | 2437 |

### External Leadframe Plating

| Item | % of Plating | Weight (g) | PPM       |
|------|--------------|------------|-----------|
| Sn   | 100          | 4.98 E-03  | 6.33 E+03 |

### Bond Wires

| Item | % of Wire | Weight (g) | PPM  |
|------|-----------|------------|------|
| Au   | 99.99     | 1.19 E-03  | 1513 |

### Chip

| Item | % of Chip | Weight (g) | PPM   |
|------|-----------|------------|-------|
| Si   | 100       | 2.97 E-02  | 37806 |

### Die Attach

| Item      | % of Die Attach | Weight (g) | PPM  |
|-----------|-----------------|------------|------|
| Resin     | 25              | 5.90 E-04  | 750  |
| Ag Filler | 75              | 1.77 E-03  | 2250 |

### Package Totals

| Weight (g) | PPM     |
|------------|---------|
| 7.87 E-01  | 1000000 |

### Molding Compound

| Item | PPM          | Method                       |
|------|--------------|------------------------------|
| Pb   | <2           | US EPA method #3052 & 6010B  |
| Cd   | Not Detected | BS EN 1122:2001 ICP AES      |
| Hg   | <2           | US EPA method #3052 & 7471A  |
| Cr+6 | <2           | US EPA method #3060A & 6010B |

### Die Attach Paste

| Item | PPM          | Method  |
|------|--------------|---------|
| Pb   | <5           | ICP AES |
| Cd   | <5           | ICP AES |
| Hg   | <5           | ICP AES |
| Cr+6 | <5           | ICP AES |
| PBB  | Not Detected |         |
| PBDE | Not Detected |         |

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability for any inaccuracy of such information.



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|------------------|----------|
| <b>Package</b>   | SOIC     |
| <b>Body Size</b> | 300 mils |
| <b>LeadCount</b> | 28       |
| <b>Option</b>    | Sn/Pb    |

### Molding Compound

| Item             | % of Compound | Weight (g) | PPM    |
|------------------|---------------|------------|--------|
| Epoxy resin      | 10            | 5.26 E-02  | 66907  |
| SiO2 Filler      | 85            | 4.47 E-01  | 568714 |
| Phenol Resin     | 3             | 1.58 E-02  | 20072  |
| Antimony_Sb2O3   | 1.5           | 7.89 E-03  | 10036  |
| Brominated Resin | 0.5           | 2.63 E-03  | 3345   |

### Leadframe

| Item | % of Leadframe | Weight (g) | PPM    |
|------|----------------|------------|--------|
| Cu   | 97.5           | 2.15 E-01  | 272841 |
| Fe   | 2.35           | 5.17 E-03  | 6576   |
| P    | 0.03           | 6.60 E-05  | 84     |
| Zn   | 0.12           | 2.64 E-04  | 336    |

### Internal Leadframe Plating

| Item | % of Plating | Weight (g) | PPM  |
|------|--------------|------------|------|
| Ag   | 100          | 1.92 E-03  | 2437 |

### External Leadframe Plating

| Item | % of Plating | Weight (g) | PPM  |
|------|--------------|------------|------|
| Sn   | 85           | 4.23 E-03  | 5382 |
| Pb   | 15           | 7.47 E-04  | 950  |

### Bond Wires

| Item | % of Wire | Weight (g) | PPM  |
|------|-----------|------------|------|
| Au   | 99.99     | 1.19 E-03  | 1513 |

### Chip

| Item | % of Chip | Weight (g) | PPM   |
|------|-----------|------------|-------|
| Si   | 100       | 2.97 E-02  | 37806 |

### Die Attach

| Item      | % of Die Attach | Weight (g) | PPM  |
|-----------|-----------------|------------|------|
| Resin     | 25              | 5.90 E-04  | 750  |
| Ag Filler | 75              | 1.77 E-03  | 2250 |

### Package Totals

| Weight (g)       | PPM            |
|------------------|----------------|
| <b>7.87 E-01</b> | <b>1000000</b> |

### Molding Compound

| Item | PPM          | Method                       |
|------|--------------|------------------------------|
| Pb   | <2           | US EPA method #3052 & 6010B  |
| Cd   | Not Detected | BS EN 1122:2001 ICP AES      |
| Hg   | <2           | US EPA method #3052 & 7471A  |
| Cr+6 | <2           | US EPA method #3060A & 6010B |

### Die Attach Paste

| Item | PPM          | Method  |
|------|--------------|---------|
| Pb   | <5           | ICP AES |
| Cd   | <5           | ICP AES |
| Hg   | <5           | ICP AES |
| Cr+6 | <5           | ICP AES |
| PBB  | Not Detected |         |
| PBDE | Not Detected |         |

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